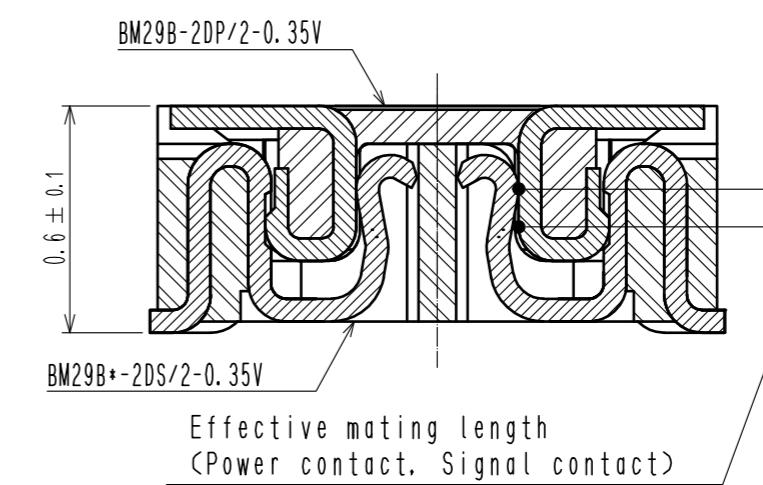
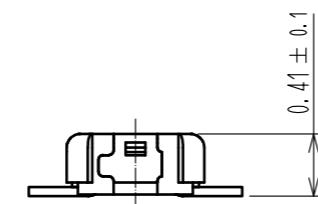
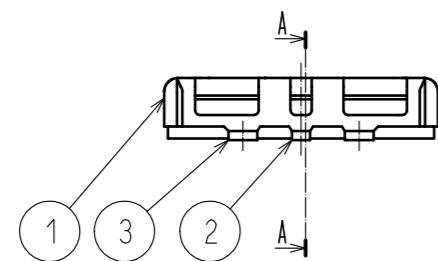
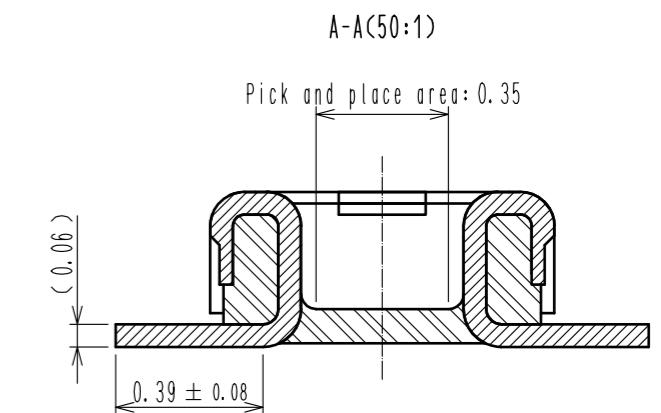
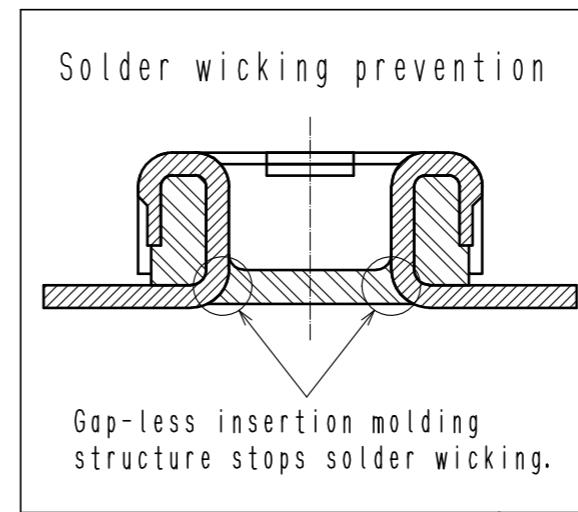
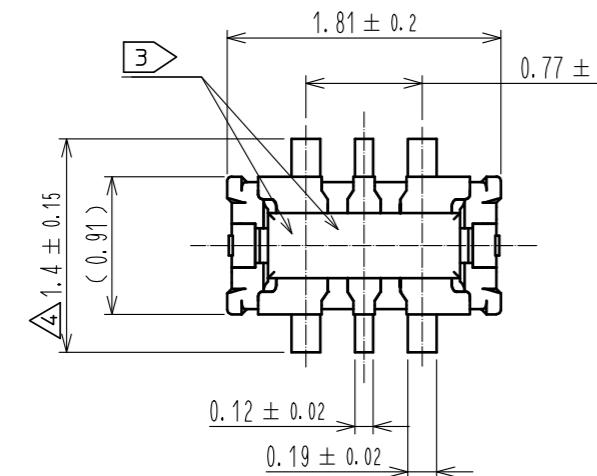


A —
B —
C —
D —
E —



⚠ NOTE 1 . All lead co-planarity will be 0.08mm MAX.

2 . Contact plating specifications

 Contact area : Gold 0.05 μm MIN

 SMT lead : Gold 0.05 μm MIN

 Under plating : Nickel 1 μm MIN

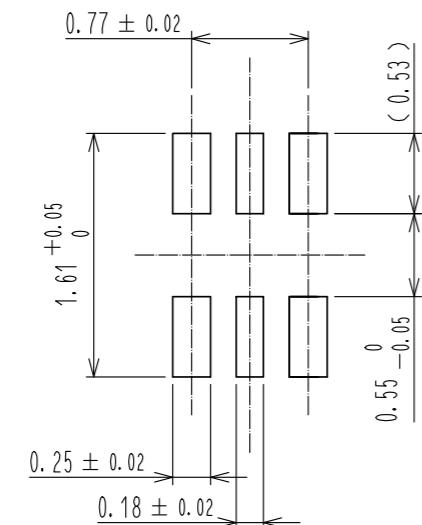
 (Surface : Sealing)

3 . Cavity number is indicated at approximate location.

3	PHOSPHOR BRONZE	2	7	PS	CLEAR. REINFORCEMENT COLLAR
2	PHOSPHOR BRONZE	2	6	PS	BLACK. PLASTIC REEL
1	LCP	UL94 V-0. BLACK	5	POLYESTER	CLEAR. COVER TAPE
NO.	MATERIAL	FINISH . REMARKS	4	PS	SMOKE GRAY. EMBOSSED CARRIER TAPE
UNITS mm		SCALE 20: 1	COUNT 4	DESCRIPTION OF REVISIONS DIS-H-00019139	DESIGNED RT. OSAKI
HIROSE ELECTRIC CO., LTD.		APPROVED : MO. ISHIDA CHECKED : KY. MIDORIKAWA DESIGNED : TY. YAMASAKI DRAWN : TY. YAMASAKI	20150323 20150323 20150323 20150323	DRAWING NO. PART NO. CODE NO.	EDC-362710-51-00 BM29B-2DP/2-0.35V(51) CL0673-7002-0-51
					1/4

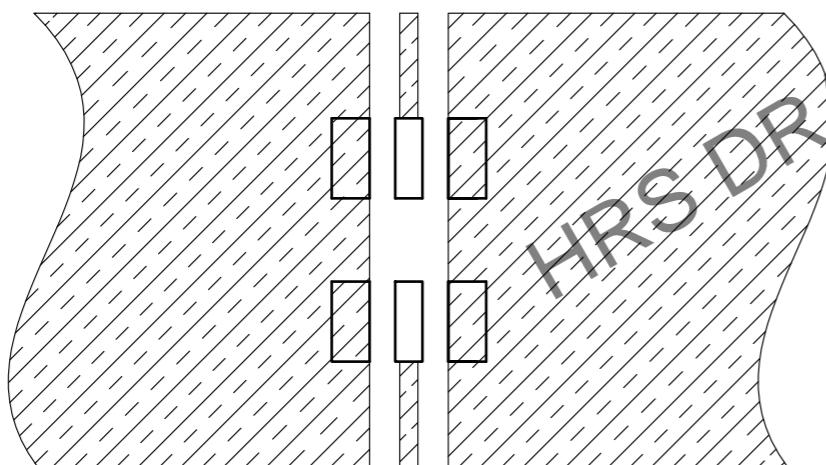
1 2 3 4 5 6 7 8

◆ Recommended PCB layout

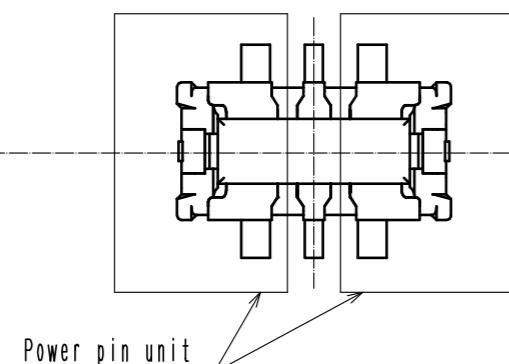


◆ Recommended metal mask dimensions
Metal mask thickness : 80 μ m
(Open ratio : 80% for PCB layout)

◆ Recommended electrical circuit layout

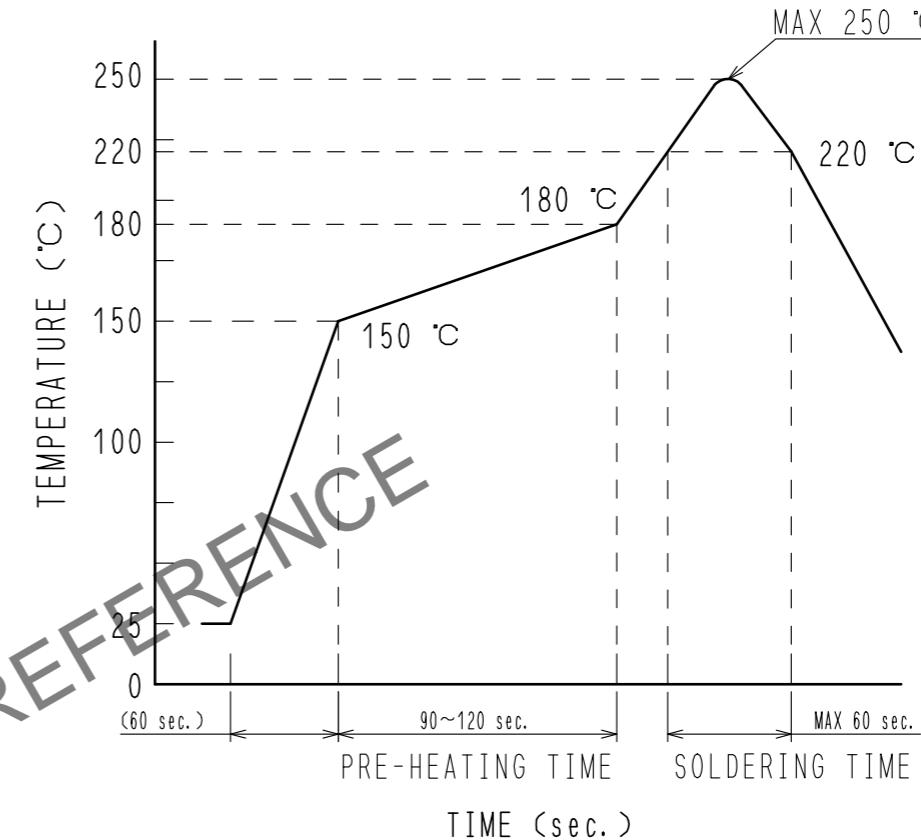


Electrical circuit



Power pin unit

4 Recommended reflow temperature profile using lead-free solder paste.



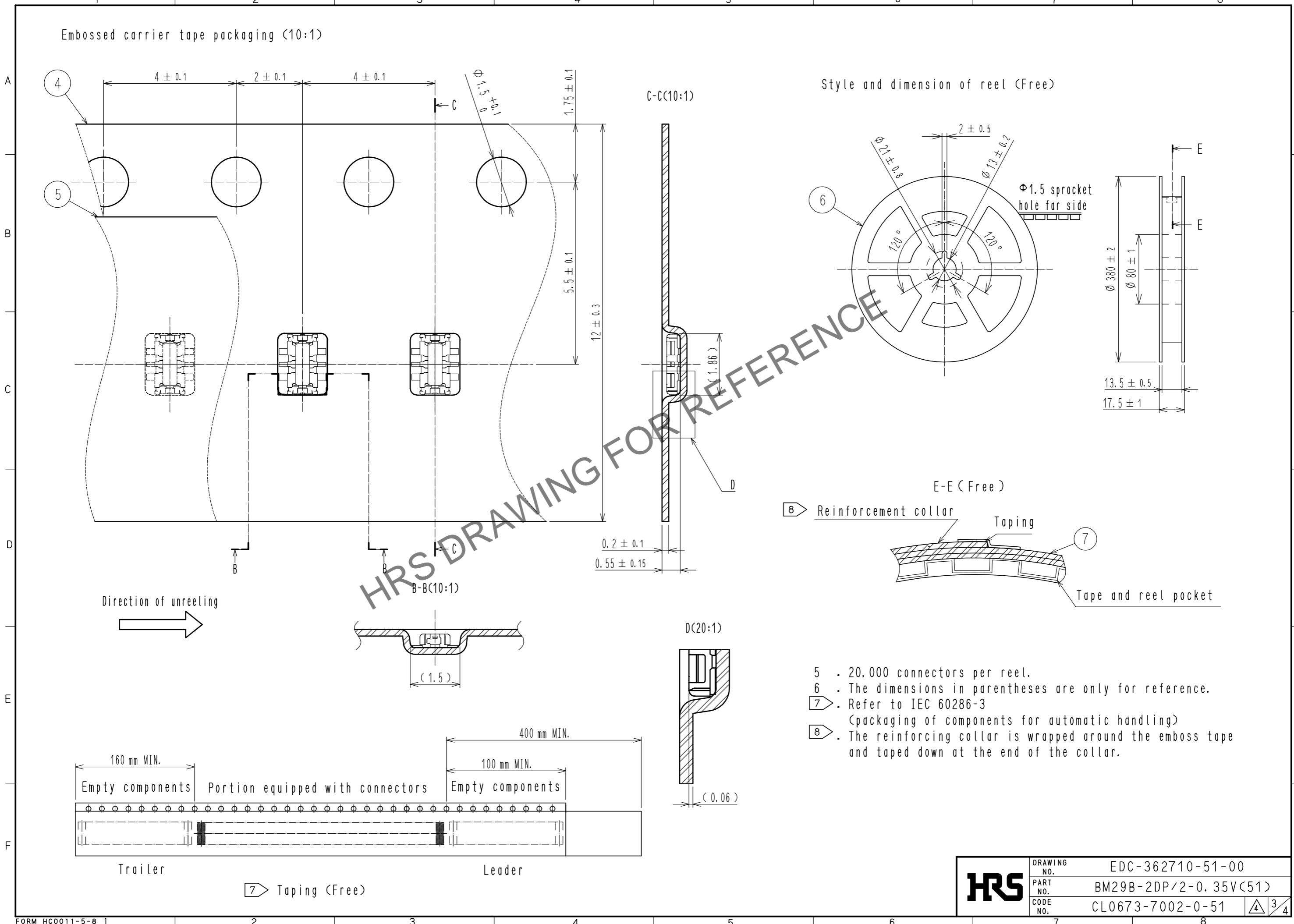
Reflow method:IR reflow
Number of reflow cycles:2 cycles MAX.

- 1) Reflow time
Duration above 220°C, 60 sec MAX.
(Peak temperature:250°C MAX)
- 2) Pre-heat time
Pre-heat temperature(MIN):150°C
Pre-heat temperature(MAX):180°C
Pre-heat time:90-120 sec.

4 This temperature profile is based on the suggested metal mask and footprint. Please contact us if using different settings from our recommendation.



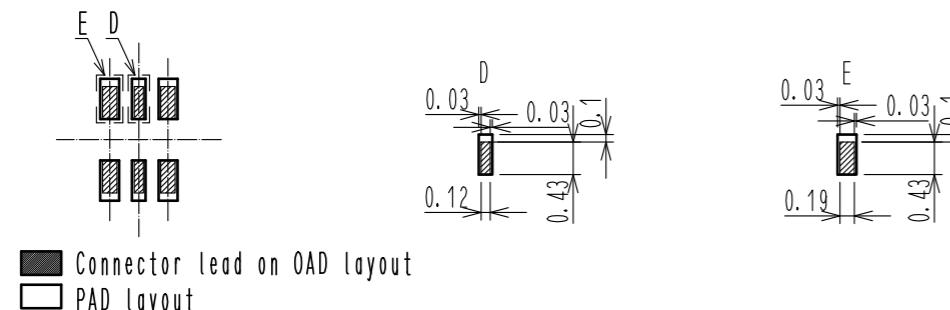
DRAWING NO. EDC-362710-51-00
PART NO. BM29B-2DP/2-0.35V(51)
CODE NO. CL0673-7002-0-51 4/2/4



9. Please refer to the product guideline ETAD-H1016 for detail of connector handling.

A

The position between the connector and PAD



B

Mating method

Please mate the connector by hand.

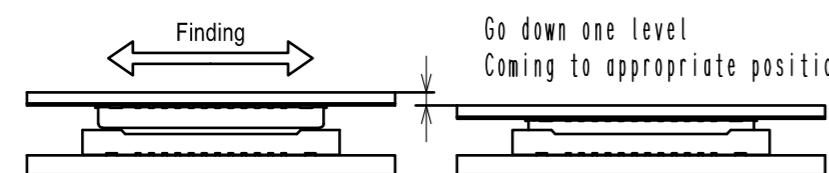
Mating procedure

(1) Find the alignment area to the connector in the appropriate mating position.

This connector has an alignment chamber (guidance ribs) on receptacle side and "r" on plug side, so that the connector will be self-aligned.

When the connector comes to the appropriate position. The connector goes into the aligned position.

When aligned, it can be felt by hand.



C

(2) When guiding, the connectors are aligned parallel to each other, with longitudinal and lateral movements restricted. Mate them properly by applying force in this condition.



D

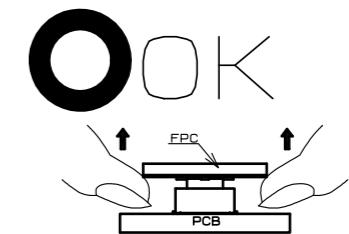
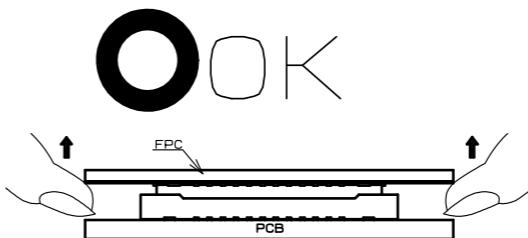
(3) Make sure the connectors are mated correctly. If one side is floating or the connectors are mated in one direction, un-mate them once, and then mate them again, following the procedures above from the beginning.

F

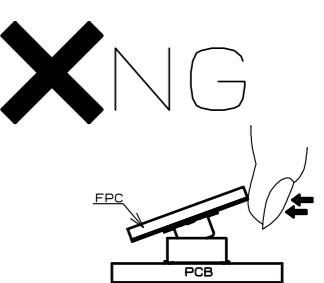
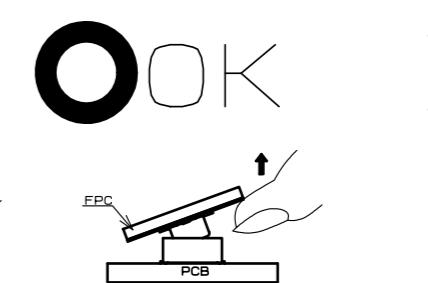
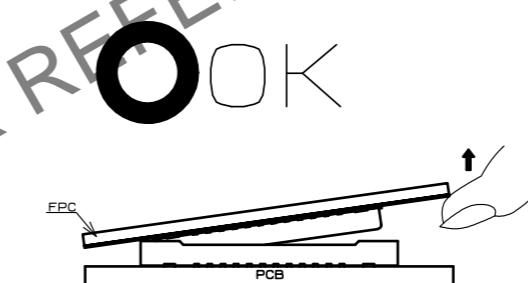
Un-mating method

Please un-mate the connector by hand

(1) Un-mate the connectors parallel to each other. However, if the connectors have high pin counts or thinner FPC and stiffener, it becomes more difficult to do so.



(2) If the connector cannot be un-mated parallel it can be removed diagonally from the pitch direction. Be careful to do so since this action applies stress on the contact.



(3) If the FPC is not rigid. The connector can be broken. Please check the action of the FPC to be used repeatedly at the time of trial production. be careful to un-mate them from the pitch direction, pulling it from the corner can also risk to putting stress on contacts.

